

# SOT903-2

plastic thermal enhanced low profile quad flat package; no leads; 64 terminals; resin based

8 February 2016

Package information

## 1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFN64R
Package type industry code	HLQFN64R
Package style descriptive code	HLQFN (thermal enhanced low profile quad flatpack; no leads)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	4-11-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.9	-	9	9.1	mm
E	package width	8.9	-	9	9.1	mm
A	seated height	1.25	-	1.35	1.4	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	64	-	

## 2. Package outline

Fig. 1. Package outline HLQFN64R (SOT903-2)



### 3. Legal information

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